



## **DirectFET Small Can**

# **RoHS Compliance Document**

Contents:

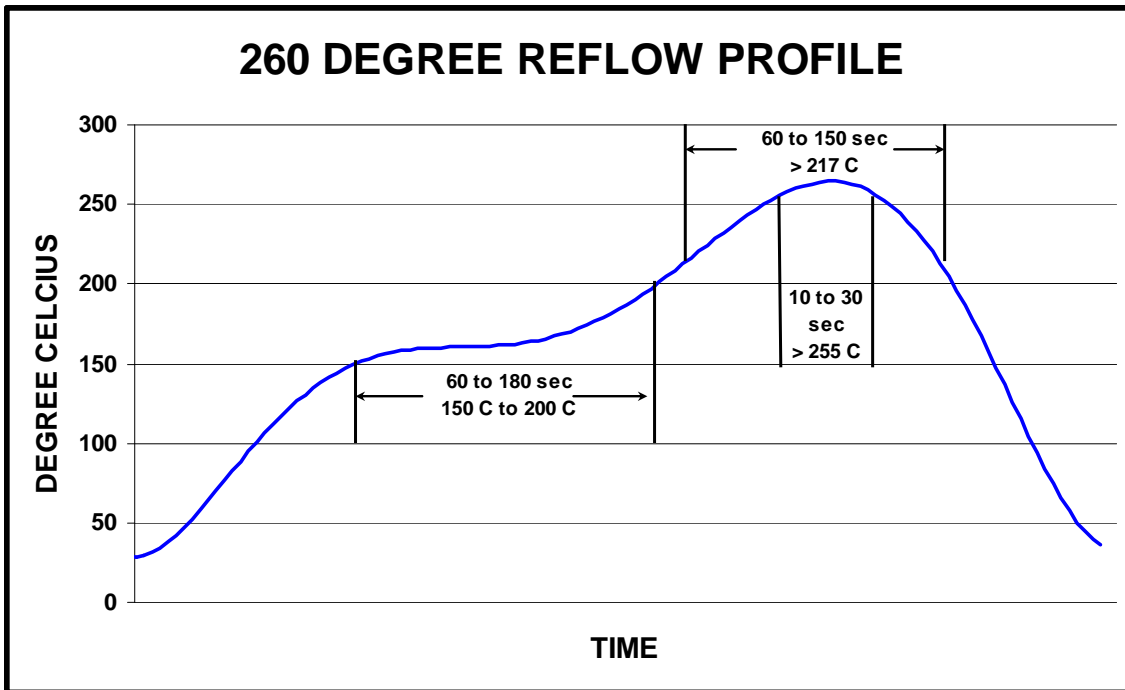
1. Composition
2. Solder Reflow



**DirectFET – Small Can**

Component	Material Name	Material Mass (g)	Substance Name	CAS Number	Substance Mass (g)	Substance Weight (%)	% of Total Weight
Chip	Silicon	0.00332	Si	7440-21-3	0.00296	89%	6.1%
			Epoxy	90598-46-2	0.00036	11%	0.7%
Lead Frame	Plated Copper	0.04304	Cu	7440-50-8	0.04190	97%	87.0%
			Ni	7440-02-0	0.00026	1%	0.5%
			Ag	7440-22-4	0.00088	2%	1.8%
Die Attach	Silver Epoxy	0.00101	Ag	7440-22-4	0.00076	75%	1.6%
			Epoxy	90598-46-2	0.00025	25%	0.5%
Solder	Solder Bumps	0.00080	Sn	7440-31-5	0.00074	93%	1.5%
			Ag	7440-22-4	0.00005	6%	0.1%
			Cu	7440-50-8	0.00001	1%	0.0%
<b>MSL3 at 260 C</b>		Total Weight (g)		<b>0.04817</b>			

No tin whisker mitigation strategy



This part is compliant with EU Directive 2002/95/EC (RoHS) and does not contain lead, mercury, cadmium (0.01%), hexavalent chromium, PBB or PBDE in concentrations greater than 0.1%, except as permitted by Annex (7).